广东惠伦晶体科技股份有限公司
GUANGDONG FAITH LONG CRYSTAL TECHNOLOGY Co.,Ltd.
NO.68 Huangjiang Donghuan Road，Huangjiang Town，Dongguan City，Guangdong Province，China
TEL :+86(0)769-38879888 Fax :+86(0)769-38879889 E-mail : yl@dgylec.com

# PRODUCT SPECIFICATION SHEET

| | | |
|---|---|---|
| CUSTOMER | : | |
| PRODUCT TYPE | : | OSC 7.0X5.0 (4PAD) |
| NOMINAL FREQ. | : | 12.288000 MHz |
| FL P/N | : | 7C12200008 |
| REVISION | : | S0 |
| CUSTOMER P/N | : | |

CUSTOMER'S APPROVAL&DATE

FL CORPORATION

| APPROVED | CHECKED | DESIGNED |
|---|---|---|
| Xing Yue | Huang Ji Ning | Li Xiang |

MSL1

RoHS Compliant

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**ATTACHMENT（optional）**

- ELECTRICAL CHARACTERISTICS TEST A ☐ YES ☑ NO
- TEMPERATURE CHARACTERISTICS TEST B ☐ YES ☑ NO

**SPECIFICATION REVISION RECORD SHEET**

| Rev. | Revise page | Revise Contents | Date | Ref. No. | Reviser |
|---|---|---|---|---|---|
| S0 | N/A | Initial released | 1-Jun-22 | N/A | Li Xiang |
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## ELECTRICAL SPECIFICATIONS

**Standard atmospheric conditions**

Unless otherwise specified. The standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature 25±2℃
Relative humidity 40%~70%

If there is no doubt the results, measurement shall be made within the following limits:

Ambient temperature 25±2℃
Relative humidity 40%~70%

**Measure equipment**

Electrical characteristics measured by S&A 280A or equivalent.

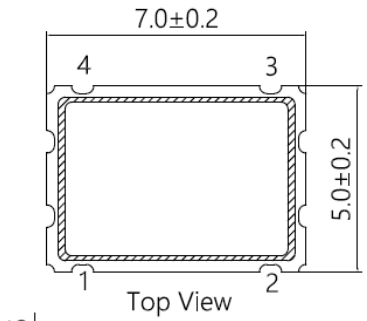
**Crystal cutting type**

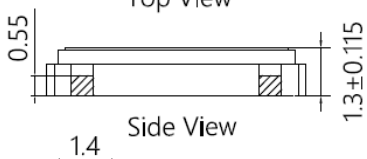
The crystal is using AT CUT (thickness shear mode)

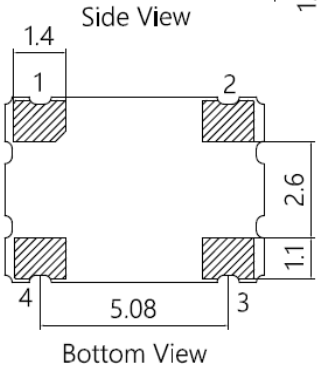
**ELECTRICAL SPECIFICATIONS**

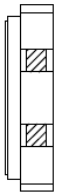
| Parameters | Symbol | Electrical Spec. | UNITS | Notes |
|---|---|---|---|---|
| Nominal Frequency | FL | 12.288000 | MHz | - |
| Operating Temperature | TOPR | -40 ~ +85 | ℃ | - |
| The Total Frequency Offset | - | +/-50 | ppm | - |
| Output Load | CL | 15.0 | p F | Max. |
| Supply Voltage | VDD | 3.3 | V | - |
| “0”Level | VOL | VDD×0.1 | V | Max. |
| “1”Level | VOH | VDD×0.9 | V | Min. |
| Enable High Voltage | ELH | VDD×0.7 | V | Min. |
| Enable Low Voltage | ELL | VDD×0.3 | V | Max. |
| Symmetry of Wave From | Symmetry | 45~55% | | - |
| Current Consumption | IDD | 10.0 | m A | Max. |
| Rise and Fall Time | Tr,Tf | 10.0 | nSec | Max. |
| Start time | tosc | 10.0 | mSec | Max. |
| Aging | - | +/-5 | ppm | 1st Year |
| Storage Temperature Range | - | -55 ~ +125 | ℃ | - |
| Output waveform | - | CMOS | - | - |
| ESD | - | HBM＞2000V | – | JESD22-A114-B |
| MSL | - | Level 1 | – | IPC/JEDEC J-STD-033C |

**DIMENSION:**



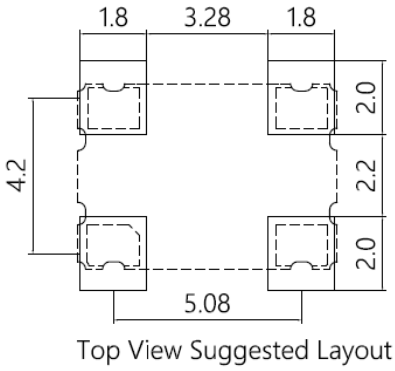



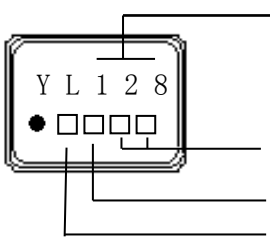
PAD FUNCTION
1: ENABLE CONTROL
2: GND
3: OUT
4: VDD

Enable Control

| Pad 1 Input | Pad 3 Output |
|---|---|
| Level High or Open | Normal Operation |
| Level Low | Stopped |




**MARKING**




**Frequency**
**Ex：128=12.28800MHz**

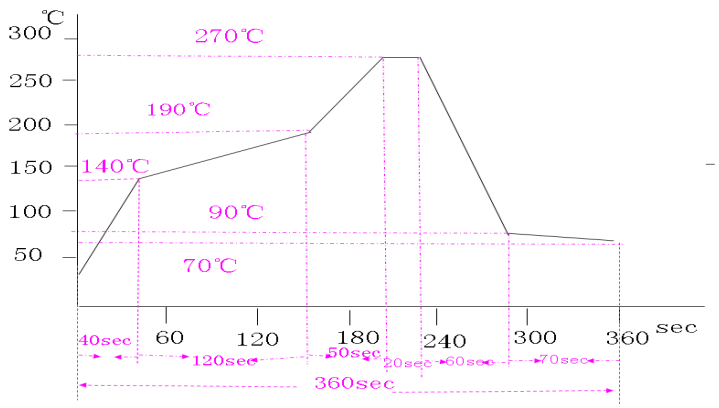
**Lot （2 digits）**
**Year Month Code**
**Administrative Symbo**

| year \ month | | JAN | FEB | MAR | APR | MAY | JUN | JUL | AUG | SEP | OCT | NOV | DEC |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| 2021 | 2025 | A | B | C | D | E | F | G | H | J | K | L | M |
| 2022 | 2026 | N | P | Q | R | S | T | U | V | W | X | Y | Z |
| 2023 | 2027 | a | b | c | d | e | f | g | h | j | k | l | m |
| 2024 | 2028 | n | p | q | r | s | t | u | v | w | x | y | z |

**SUGGESTED REFLOW PROFILE**

Total time : 360 sec. Max.

Solder melting point :185 $^{o}$C



## RELIABILITY SPECIFICATIONS

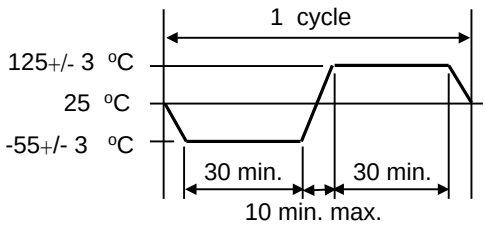
1.MECHANICAL ENDURANCE

| No. | Test Item | Test Methods | | |
|---|---|---|---|---|
| 1 | Drop Test | 75 cm height, fall freely onto stainless plate 3 times. | | JIS C6701 |
| 2 | Mechanical Shock | Device are shocked to half sine wave ( 1000 G ) three mutually pendicular axes each 3 times. 0.5m sec. duration time | | MIL-STD-202F |
| 3 | Vibration | Frequency range<br>Amplitude<br>Sweep time<br>Pendicular axes each test time | 10 ~ 2000 Hz<br>1.52 mm<br>20 minute<br>4 hours<br>(Total test time 12 hours) | MIL-STD-883E |
| 4 | Solderability | Temperature<br>Immersing depth<br>Immersion time<br>Flux | 260 °C +/- 5 °C , 5 +/-1 sec<br>0.5 mm minimum<br>10 +/- 0.5 seconds<br>Rosin resin methyl alcohol solvent ( 1 : 4 ) | MIL-STD-883E |
| 5 | Resistance To Soldering Heat | Pre-heat temperature<br>Pre-heat time<br>Test temperature<br>Test time | 125 °C<br>60 ~ 120 sec.<br>260 +/- 5 °C<br>5 +/- 1 sec. | MIL-STD-202F |

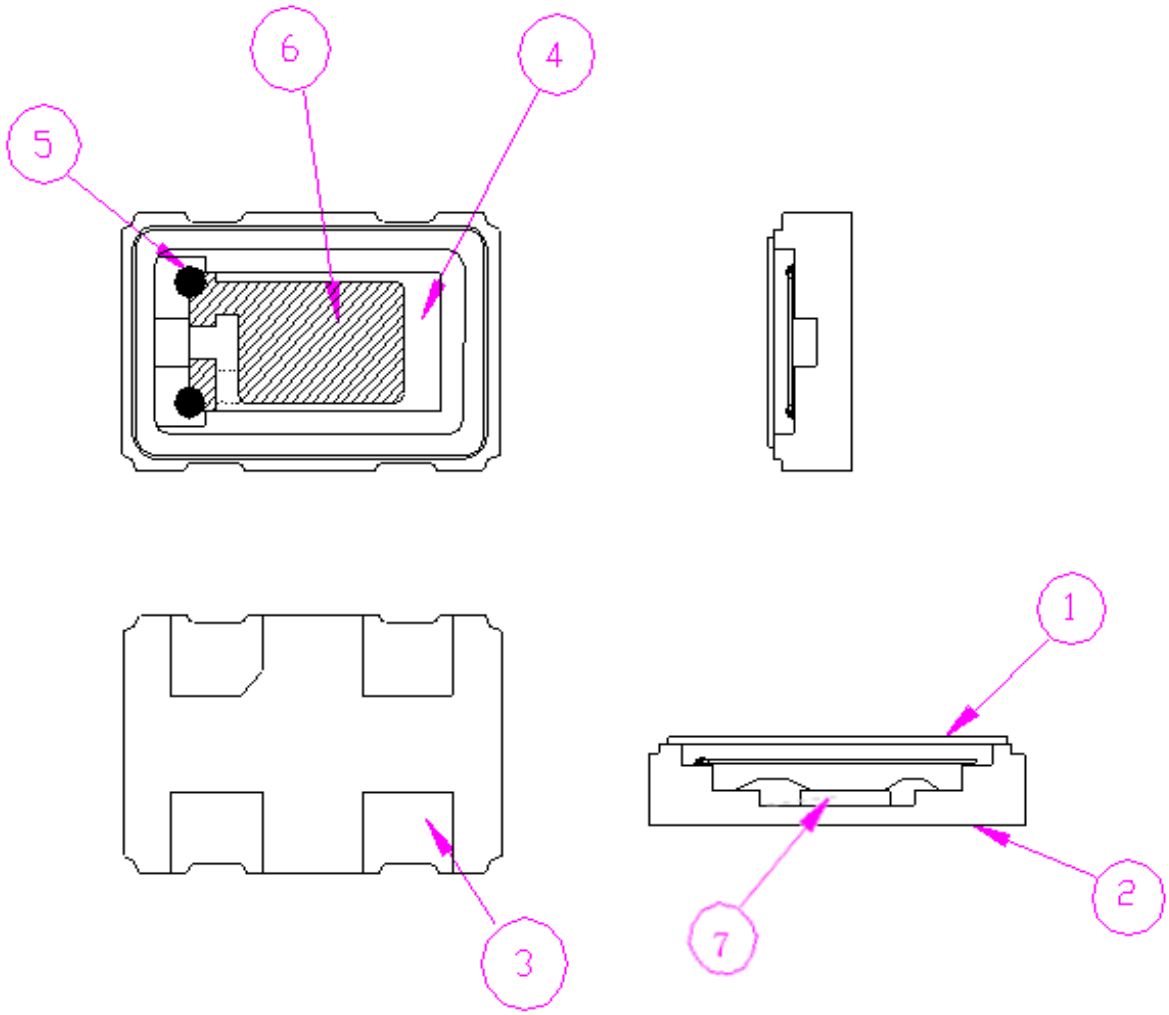
*Storage conditions ： 18 months

*Constant humidity ： 40~70%

2.ENVIRONMENTAL ENDURANCE

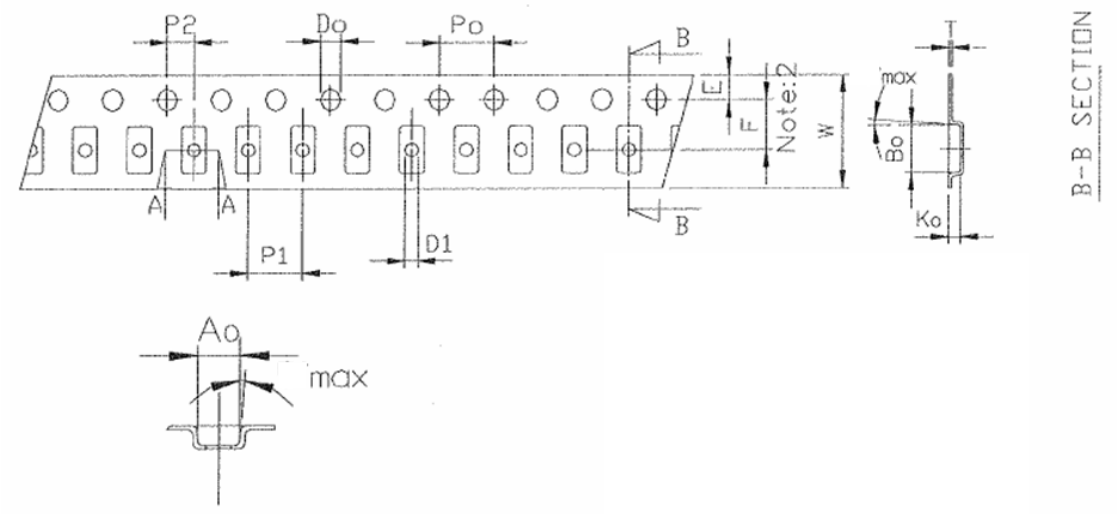
| No. | Test Item | Test Methods | |
|---|---|---|---|
| 6 | High Temp. Storage | + 125 °C +/- 2 °C for 1000 +/- 12 hours | MIL-STD-883E |
| 7 | Low Temp. Storage | - 40 °C +/- 2 °C for 1000 +/- 12 hours | |
| 8 | Thermal Shock | Total 10 cycles of the following temperature cycle   | MIL-STD-883E |
| 9 | High Temp. Operation | + 85°C, VCC, for 1000 hours | MIL-STD-883E |
| 10 | Low Temp. Operation | - 40°C, VCC, for 1000 hours | MIL-STD-883E |

## STRUCTURE ILLUSTRATION




| NO | COMPONENTS | MATERIALS | QTY | FINISH/SPECIFICATIONS |
|---|---|---|---|---|
| 1 | Cap (Lid) | Metal (Fe) | 1 | - |
| 2 | Base (Package) | Ceramic ($Al_2O_3$) | 1 | Alumina ceramics |
| 3 | Pad (Package) | Au | 4 | Tungsten metalize<br>+Ni plating<br>+Au plating |
| 4 | Crystal blank | $SiO_2$ | 1 | - |
| 5 | Conductive adhesive | Ag | 4 | Silicone resin |
| 6 | Electrode | Noble metal | 2 | - |
| 7 | IC | Silicon (Si) | 1 | - |

**PACKING : (EIA-481-2)**




| Dimension / PKG Type | Unit : mm | | | | | | |
|---|---|---|---|---|---|---|---|
| | **A0** | **B0** | **K0** | **T** | **W** | **E** | **F** |
| **7050(16mm)** | 5.45±0.1 | 7.9±0.1 | 2±0.1 | 0.3±0.05 | 16±0.2 | 1.75±0.2 | 7.5±0.2 |
| | **P1** | **P2** | **D1** | **D0** | **P0** | | |
| | 8±0.2 | 2±0.1 | 1.55±0.1 | 1.55±0.05 | 4±0.1 | | |

Standard Reel Quantity is 1,000 pcs per reel.

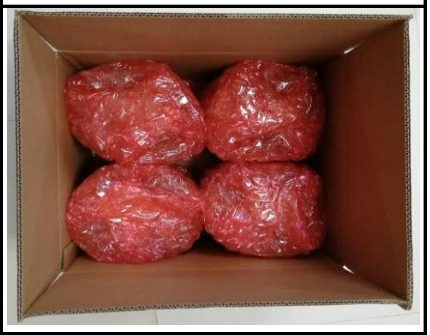
**THE INSPECTION FOR TAPE TENSION**

| ITEM | | Defect | Method |
|---|---|---|---|
| Appearance | ALL | 1.The tape is not coincidence<br>2.The bubble | Visual inspection |
| Tape Tension | 8045、7050<br>6035-12mm<br>5032-12mm<br>3225-12mm | overstep 61±6g(55～67g) | Pull test |
| | 3225-8mm | overstep 40±5g(35～45g) | |
| | 2520-8mm | overstep 55±6g(49～61g) | |
| | 2016-8mm | overstep 34±6g(28～40g) | |
| | 1612-8mm | overstep 34±6g(28～40g) | |
| | 6035-16mm<br>5032-16mm | overstep 60±6g(54～66g) | |

**REMARK : NA**

## SMD PRODUCT PACKING STANDARD

### Out-going packing instruction

| Reel Packing | Inner Packing | Carton |
|---|---|---|
| name：reel<br>standard：diameter 18cm<br>material：plastics<br>name：Anti-Static Shielding Bag<br>standard：205×250mm<br>material：APET/CPP | name：Anti-Static Bubble Bags<br>standard：430x330+20mm<br>material：HDPE(15 reels enter) | name：carton<br>standard：400x400x280mm<br>material：AB corrugated paper (40 boxes enter) |
|  |  |  |
|  |  |  |

### The label instruction

| Label Drawing | Mark | Name of Article | Spec. | Size | Printing |
|---|---|---|---|---|---|
|  | L1 | 条码标签<br>Bar Code<br>Label<br>(Chintz Paper) | 1.Part No.<br>2.Lot No.<br>3.Q'ty<br>4.Freq | 70x50mm | White |
|  | L2 | 条码标签<br>Bar Code<br>Label<br>(Chintz Paper) | 1.Part No.<br>2.Date Code<br>3.Q'ty<br>4.Freq | 70x50mm | White |

**Remark**

Specifications on the label is for the use of templates with different product specifications may vary.
If customer specified requirements for labels packaging. please provide the operation procedure.

| Range | Products | Packing Material |
|---|---|---|
| **Banned Substances** | **Maximum concentration ppm(mg/kg)** | **Maximum concentration ppm(mg/kg)** |
| 1.镉及镉化合物<br>Cadmium and cadmium compounds | 100 | 100 |
| 2.铅及铅化合物<br>Lead and lead compounds | 1000 | 100 |
| 3.汞及汞化合物<br>Mercury and mercury compounds | 1000 | 100 |
| 4.六价铬化合物<br>Hexavalent-Chromium VI (Cr+6) | 1000 | 100 |
| 5.聚溴联苯 PBB<br>Polybrominated biphenyls | 1000 | N/A |
| 6.聚溴二苯醚 PBDE<br>Polybrominated diphenyl ethers | 1000 | N/A |
| 7.邻苯二甲酸二(2-乙基己基)酯 DEHP<br>Di (2-ethylhexyl) phthalate | 1000 | N/A |
| 8.邻苯二甲酸丁苄酯 BBP<br>Butyl Benzyl Phthalate | 1000 | N/A |
| 9.邻苯二甲酸二丁酯 DBP<br>Dibutyl Phthalate | 1000 | N/A |
| 10 邻苯二甲酸二异丁酯 DIBP<br>Diisobutyl Phthalate | 1000 | N/A |
| 11. 氟（F）、氯（Cl）、溴（Br）、碘（I）<br>Fluorine、Chlorine、 Bromine、Iodine | 900、900、900、900<br>注：Br+Cl＜1000 | N/A |
| 12.包装材料中重金属(汞、镉、六价铬、铅、PBB、PBDE)之总量<br>Heavy metals (mercury, cadmium, lead, Cr+6,PBB and PBDE) in packing materials | N/A | 100<br>铅(Pb) + 镉(Cd) + 汞(Hg) + 六价铬(Cr+6) <100ppm |
| 13.高度关注物质<br>SVHC-Substances of Very High Concern | 1000 | N/A |


惠伦晶体
FAITH LONG CRYSTAL